

App. No. 10/604,512
Response dated October 5, 2005
Reply to Office Action of July 5, 2005

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the present application.

Listing of Claims:

Claim 1 (currently amended): A wafer holder for semiconductor manufacturing equipment, the wafer holder having a surface for carrying wafers of a predetermined diameter and comprising:

a high-frequency RF power-generating electrode circuit round in form, built into the wafer holder, the electrode circuit diameter being 90% or more of the greater than said predetermined diameter of the wafers that the wafer holder carries.

Claim 2 (canceled)

Claim 3 (original): A wafer holder as set forth in claim 1, wherein the distance between the periphery of the high-frequency RF power-generating electrode circuit built into the wafer holder and the periphery of the wafer holder is longer than the distance separating said electrode circuit from the wafer-carrying surface.

Claim 4 (currently amended): Semiconductor manufacturing equipment wherein the wafer holder set forth in claim [[2]] 1 is installed.

Claim 5 (original): Semiconductor manufacturing equipment wherein the wafer holder set forth in claim 3 is installed.